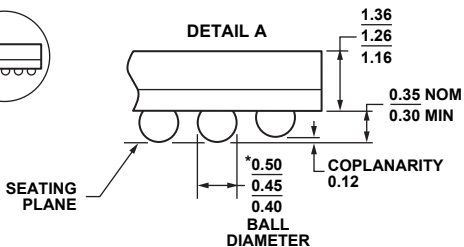
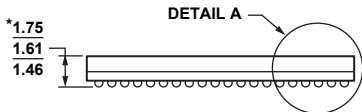
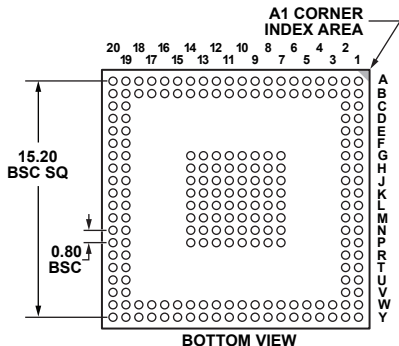
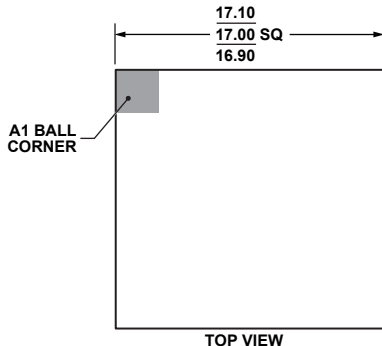


# 208-Ball Chip Scale Package Ball Grid Array [CSP\_BGA]

(BC-208-2)

Dimensions shown in millimeters



\*COMPLIANT TO JEDEC STANDARDS MO-205-AM WITH  
EXCEPTION TO PACKAGE HEIGHT AND BALL DIAMETER.

